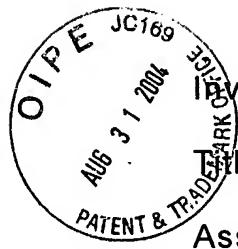


EV372460614



1 Inventor: **Salman Akram**
Title: **Board-on-Chip Packages**
Assignee: **Micron Technology, Inc.**

Serial No.: **10/772,204**

Filed: **February 3, 2004 [RCE Filed Herewith]**

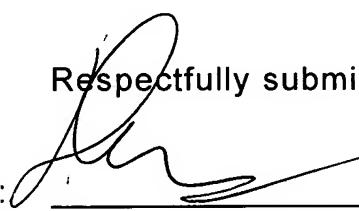
Docket No. **MI22-2499**

INFORMATION DISCLOSURE STATEMENT

References – See Attached Form PTO-1449

The attached form PTO-1449 is submitted in compliance with 37 CFR § 1.56. Copies of the cited art are included with the exception of U.S. patents and published U.S. applications (1273 Off. Gaz. Pat. Off. 55, 05 August 2003). No admission is made regarding whether all the submitted references are prior art.

Dated: 8/3/04

Respectfully submitted,
By: 

David G. Latwesen, Ph.D.
Reg. No. 38,533



EV372460614 Sheet 1 of 3

Form PTO-1449

AUG 31 2004

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PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO.
MI22-2499

SERIAL NO.
10/772,204

APPLICANT
Salman Akram

FILING DATE
Feb. 3, 2004 [RCE filed herewith]

GROUP
2826

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| | AT | | Tummala et al.; Microelectronics Packaging Handbook; 1997, Chapman & Hall Volume III; pps. 223-234. |

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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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|--|----|-----------------|------|---------|-------|----------|-------------|----|
| | | | | | | | Yes | No |
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| | AL | | | | | | | |
| | AM | | | | | | | |

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